

SOT362-1

plastic thin shrink small outline package; 48 leads; body width 6.1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP48
Package type industry code	TSSOP48
Package style descriptive code	TSSOP (thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	19-2-2003

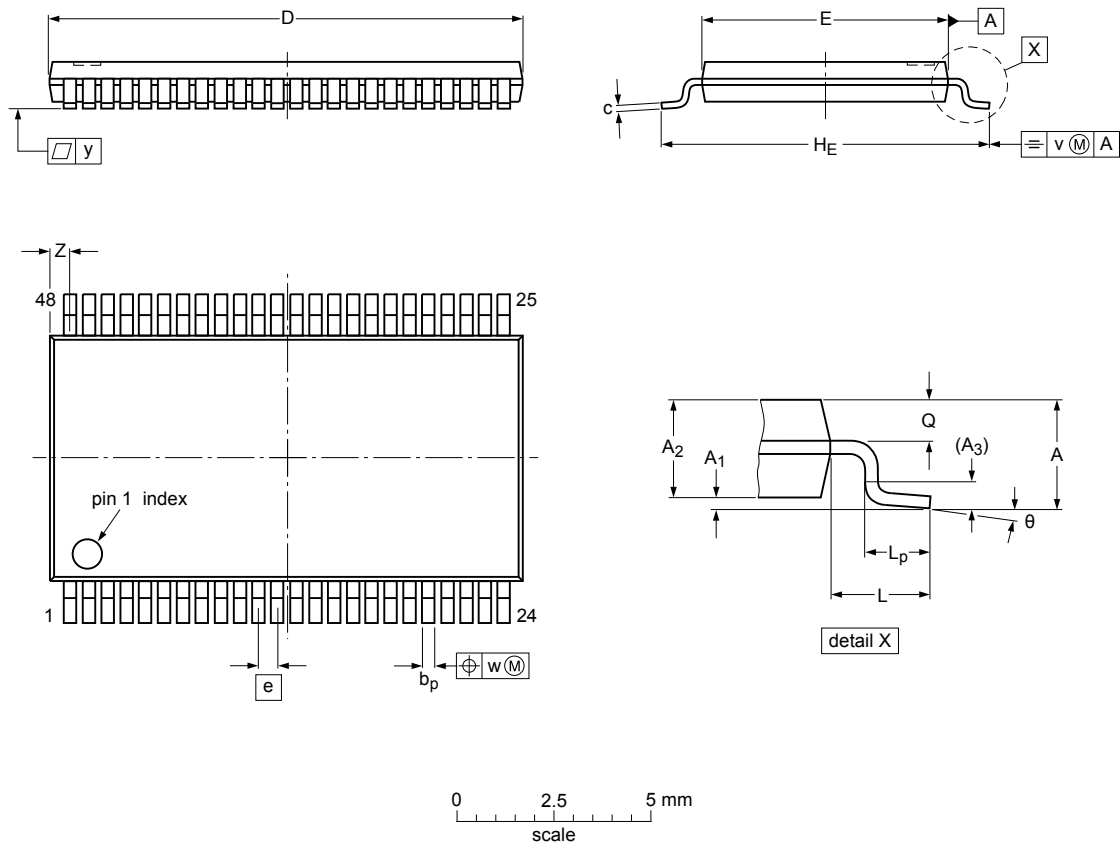
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	12.4	-	12.5	12.6	mm
E	package width	6	-	6.1	6.2	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.85	-	0.9	1.05	mm
n ₂	actual quantity of termination	-	-	48	-	



2. Package outline

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm SOT362-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z	θ
max		0.15	1.05		0.28	0.2	12.6	6.2		8.3		0.8	0.50				0.8	8°
nom	1.2			0.25					0.5		1			0.25	0.08	0.1		
min		0.05	0.85		0.17	0.1	12.4	6.0		7.9		0.4	0.35				0.4	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot362-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT362-1		MO-153			-03-02-19- 13-08-05

Fig. 1. Package outline TSSOP48 (SOT362-1)

3. Soldering

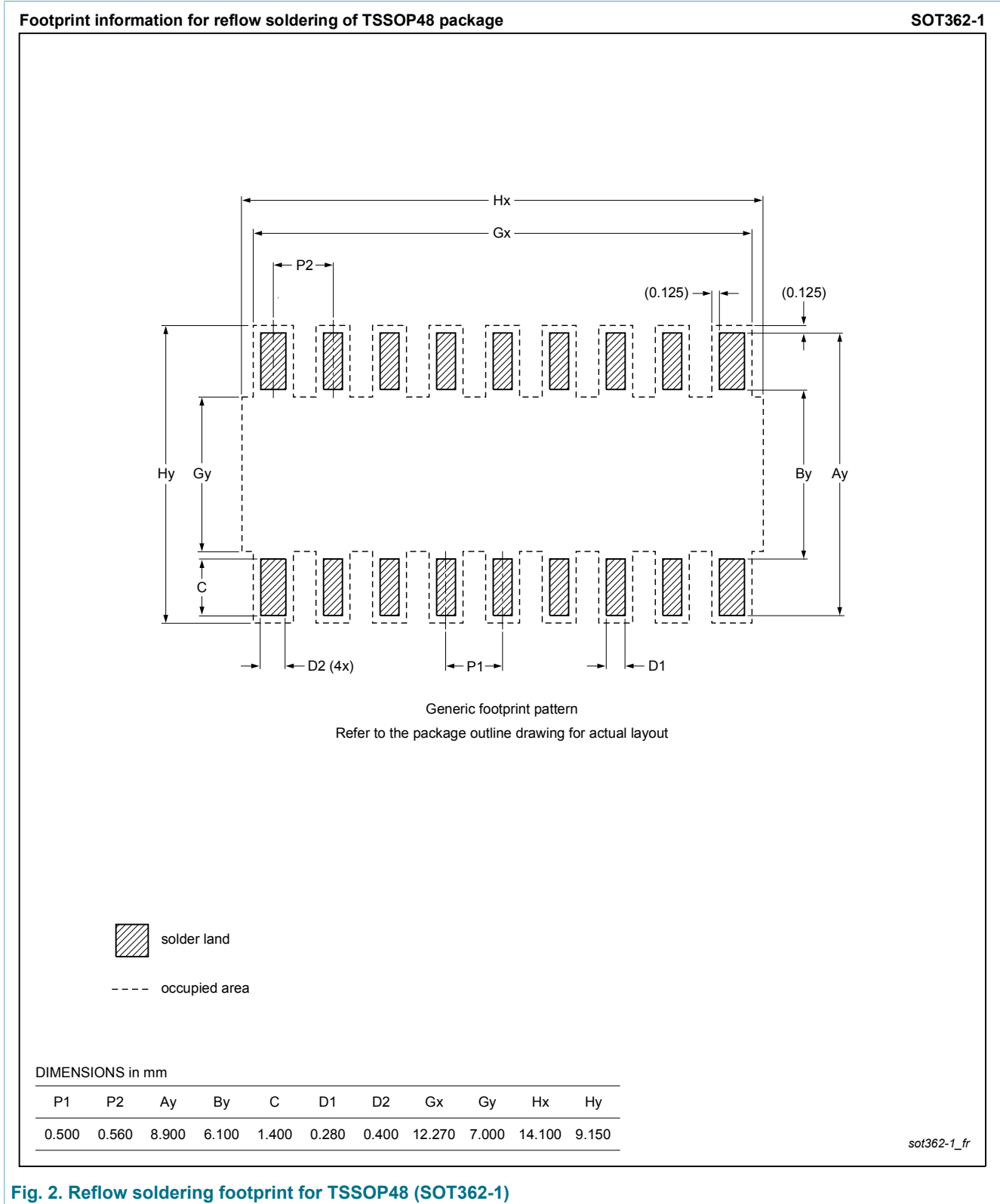


Fig. 2. Reflow soldering footprint for TSSOP48 (SOT362-1)

4. Legal information

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